

03500.011946

PATENT APPLICATION

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of:)
 : Examiner: C. Dexter
 Akira FUNAKOSHI et al.)
 : Group Art Unit: 3724
 Application No.: 08/801,464)
 :
 Filed: February 18, 1997)
 :
 For: SUBSTRATE CUTTING METHOD AND) July 23, 2002
 SUBSTRATE CUTTING APPARATUS :

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COMMISSIONER FOR PATENTS
 Washington, D.C. 20231

Sir:

Transmitted herewith is an Amendment in the above-identified application.

☒ No additional fee is required.

The fee has been calculated as shown below:

CLAIMS AS AMENDED						
	CLAIMS REMAINING AFTER AMENDMENT		HIGHEST NO. PREVIOUSLY PAID FOR	PRESENT EXTRA	RATE	ADDITIONAL FEE
TOTAL CLAIMS	9	MINUS	34	0	x \$ 9 \$18	\$0.00
INDEP. CLAIMS	2	MINUS	6	0	x \$42 \$84	\$0.00
Fee for Multiple Dependent claims \$135°/\$270						
TOTAL ADDITIONAL FEE FOR THIS AMENDMENT---						\$0.00

☐ °Verified Statement claiming small entity status is enclosed, if not filed previously.

- ☐ A check in the amount of \$_____ is enclosed including the additional claims fees.
- ☐ Charge \$____ to Deposit Account No. 06-1205. A duplicate of this sheet is enclosed.
- ☒ Any prior general authorization to charge an issue fee under 37 C.F.R. § 1.18 to Deposit Account No. 06-1205 is hereby revoked. The Commissioner is hereby authorized to charge any additional fees under 37 C.F.R. §§ 1.16 and 1.17 which may be required during the entire pendency of this application, or to credit any overpayment, to Deposit Account No. 06-1205. A duplicate of this paper is enclosed.
- ☐ A check in the amount of \$_____ to cover the Extension fee for response within _____ additional months is enclosed.
- ☐ A check in the amount of \$____ to cover the Information Disclosure Statement fee is enclosed.
- ☒ Applicants' undersigned attorney may be reached in our Washington, D.C. office by telephone at (202) 530-1010. All correspondence should continue to be directed to our address given below.

Respectfully submitted,



Attorney for Applicants
Steven E. Warner
Registration No. 33,326

FITZPATRICK, CELLA, HARPER & SCINTO
30 Rockefeller Plaza
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AMENDMENT

Sir:

In response to the Official Action dated April 23, 2002, please amend the above-identified application as follows:

IN THE ABSTRACT:

Please substitute the following abstract for the abstract currently presented in the specification. A marked-up copy of the abstract showing the changes made thereto is attached in

Appendix A.

F1 ~~30~~
-- A method of producing a semiconductor device constructed by arranging a plurality of substrates, on each of which, thin film semiconductor elements two-dimensionally arranged